





Features

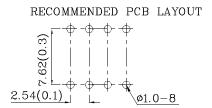
- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons

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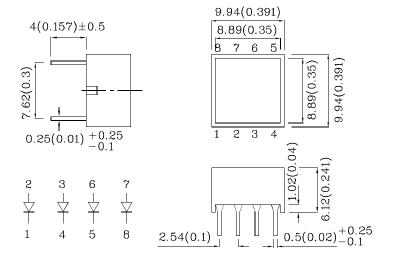
- Excellent for flush mounting
- RoHS compliant







Package Schematics



1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.

2. Specifications are subject to change without notice.

| Absolute Maximum Ratings (T _A =25°C) | UR (GaAsP/GaP) | Unit | | |
|--|-----------------------|-----------|----|--|
| Reverse Voltage | V_{R} | 5 | V | |
| Forward Current | I_{F} | 30 | mA | |
| Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width | ifs | 160 | mA | |
| Power Dissipation | P_{D} | 75 | mW | |
| Operating Temperature | T_{A} | -40 ~ +85 | °C | |
| Storage Temperature | Tstg | -40 ~ +85 | | |
| Lead Solder Temperature [2mm Below Package Base] | 260°C For 3-5 Seconds | | | |

| Operating Characteristics (T _A =25°C) | | UR (GaAsP/GaP) | Unit |
|--|---------------------|-------------------|------|
| Forward Voltage (Typ.) (I _F =20mA) | V_{F} | 2 | V |
| Forward Voltage (Max.) (I _F =20mA) | | 2.5 | V |
| Reverse Current (Max.) (V _R =5V) | I_R | 10 | uA |
| Vavelength of Peak (mission CIE127-2007* (Typ.) λP 627* $\epsilon_F = 20 \text{mA}$) | | 627* | nm |
| Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA) | λD | 617* | nm |
| Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA) | $\triangle \lambda$ | 45 | nm |
| Capacitance (Typ.) (V _F =0V, f=1MHz) | С | 15 | pF |

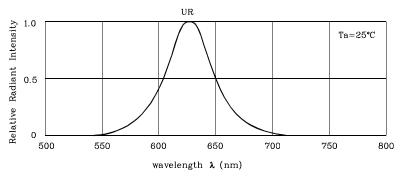
| Part Number | Emitting Color | Emitting Material | $\begin{array}{c} Luminous \ Intensity \\ CIE127\text{-}2007* \\ (I_F\text{=}20\text{mA}) \ mcd \end{array}$ | | Wavelength CIE127-2007* nm λP | Lens-color |
|----------------|-------------------|----------------------|--|-----------|-------------------------------------|----------------|
| | | | min. | typ. | | |
| XEUR2655M | Red | GaAsP/GaP | 40 8* | 69 20* | 627* | White Diffused |

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Mar 06,2014 XDSA1967 V7-X Layout: Maggie L.

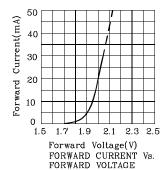


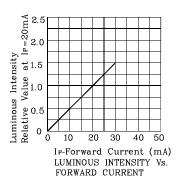


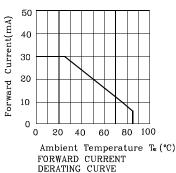


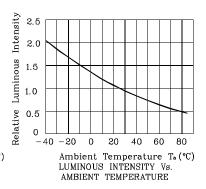
RELATIVE INTENSITY Vs. CIE WAVELENGTH

❖ UR

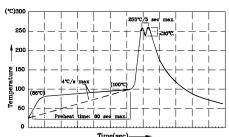








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- nmend pre-heat temperature of 105°C or less (as measured with a nocouple attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 260°C wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec
- 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 secmax).
 3.Do not apply stress to the epoxy resin while the temperature is a 4.Fixtures should not incur stress on the component when mounting during soldering process.
 5.SAC 305 solder alloy is recommended.
 6.No more than one wave soldering pass.
 7.During wave soldering, the PCB top-surface temperature should be kept below 105°C.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

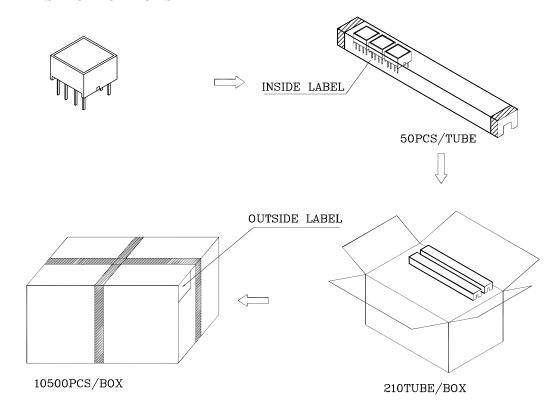
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

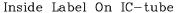
Note: Accuracy may depend on the sorting parameters.

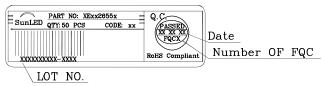




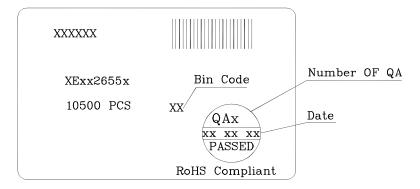
PACKING & LABEL SPECIFICATIONS







Outside Label On Box



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Mar 06,2014